

ABSTRACT OF THE DISCLOSURE

A high-frequency multilayer circuit substrate having a plurality of circuit layers includes a via hole for connection between the circuit layers, a metal pad, an impedance matching transmission line, rectangular stubs and a signal transmission line. A via hole connecting portion is constructed of the via hole, the rectangular stubs and the impedance matching transmission line. A characteristic impedance of the via hole connecting portion is matched to a characteristic impedance of the signal transmission line by adjusting widths and lengths of the impedance matching transmission line and the rectangular stubs. Thereby, the reflection of the signal wave in the via hole connecting portion is reduced to decrease a transmission loss.

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